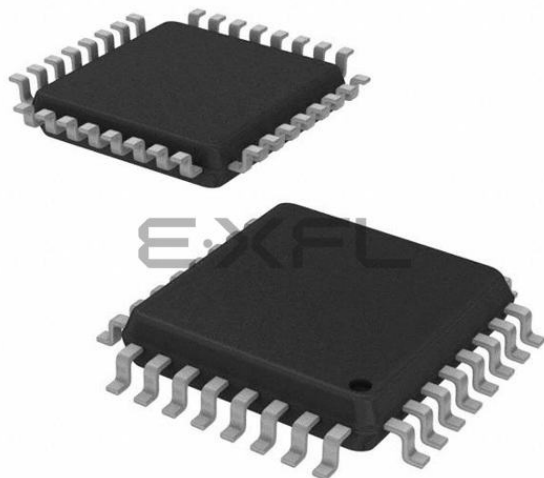




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Details

Product Status	Active
Core Processor	12V1
Core Size	16-Bit
Speed	25MHz
Connectivity	IrDA, LINbus, SCI, SPI
Peripherals	LVD, POR, PWM, WDT
Number of I/O	16
Program Memory Size	48KB (48K x 8)
Program Memory Type	FLASH
EEPROM Size	512 x 8
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	3.13V ~ 5.5V
Data Converters	A/D 2x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	32-LQFP
Supplier Device Package	32-LQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/s9s12vr48af0vlc

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1.4.4 Main External Oscillator (XOSCLCP)

- Loop control Pierce oscillator using 4 MHz to 20 MHz crystal
 - Current gain control on amplitude output
 - Signal with low harmonic distortion
 - Low power
 - Good noise immunity
 - Eliminates need for external current limiting resistor
 - Transconductance sized for optimum start-up margin for typical crystals
 - Oscillator pins shared with GPIO functionality

1.4.5 Internal RC Oscillator (IRC)

- Factory trimmed internal reference clock
 - 1 MHz internal RC oscillator with $\pm 1.3\%$ accuracy over rated temperature range

1.4.6 Internal Phase-Locked Loop (IPLL)

- Phase-locked-loop clock frequency multiplier
 - No external components required
 - Reference divider and multiplier allow large variety of clock rates
 - Automatic bandwidth control mode for low-jitter operation
 - Automatic frequency lock detector
 - Configurable option to spread spectrum for reduced EMC radiation (frequency modulation)
 - Reference clock sources:
 - Internal 1 MHz RC oscillator (IRC)

1.4.7 Clock and Power Management Unit (CPMU)

- Real time interrupt (RTI)
- Clock monitor (CM)
- System reset generation

1.4.8 System Integrity Support

- Power-on reset (POR)
- Illegal address detection with reset
- Low-voltage detection with interrupt or reset
- Computer operating properly (COP) watchdog with option to run on internal RC oscillator
 - Configurable as window COP for enhanced failure detection
 - Can be initialized out of reset using option bits located in flash memory

- 6-pin port AD with pin interrupts and wakeup function; associated with 6 ADC channels
- 4-pin port L with pin interrupts and wakeup function; associated with 4 high-voltage inputs for digital or analog use with optional voltage divider bypass and open input detection

For S12VR32/16:

- 2-pin port E associated with the external oscillator
- 4-pin port T associated with 4 TIM channels and 2 PWM channels
- 2-pin port S associated with 1 SCI
- 2-pin port P with pin interrupts and wakeup function; associated with
 - $\overline{\text{XIRQ}}$ interrupt input
 - 2 PWM channels with one of those capable of driving up to 10 mA
 - One output with over-current protection and interrupt capable of supplying up to 20 mA to external devices such as Hall sensors
- 2-pin port AD with pin interrupts and wakeup function; associated with 2 ADC channels
- 4-pin port L with pin interrupts and wakeup function; associated with 4 high-voltage inputs for digital or analog use with optional voltage divider bypass and open input detection

Most I/O pins can be configured by register bits to select data direction and to enable and select pullup or pulldown devices.

2.1.2 Features

The PIM includes these distinctive registers:

- Data registers and data direction registers for Ports E, T, S, P and AD when used as general-purpose I/O
- Control registers to enable/disable pull devices and select pullups/pulldowns on Ports T, S, P, AD on per-pin basis
- Single control register to enable/disable pullups on Port E on per-port basis and on BKGD pin
- Control registers to enable/disable open-drain (wired-or) mode on Port S
- Control register to enable/disable reduced output drive on Port P high-current pins
- Interrupt flag register for pin interrupts on Port P, L and AD
- Control register to configure $\overline{\text{IRQ}}$ pin operation
- Control register to enable ECLK clock output
- Routing registers to support module port relocation and control internal module routings:
 - PWM and ETRIG to alternative pins
 - SPI $\overline{\text{SS}}$ and SCK to alternative pins (S12VR64/48 only)
 - SCI1 to alternative pins (S12VR64/48 only)
 - HSDRV and LSDRV control selection from PWM, TIM or related register bit
 - Various SCI0-LINPHY routing options supporting standalone use and conformance testing
 - Optional LINPHY to TIM link

Port	Pin Name	Pin Function & Priority ¹	I/O	Description	Pin Function after Reset
S	PS5	<u>SS</u>	I/O	SPI slave select	GPIO
		<u>PTS[5]</u>	I/O	General-purpose	
	PS4	<u>SCK</u>	I/O	SPI serial clock	
		<u>PTS[4]</u>	I/O	General-purpose	
	PS3	ECLK	O	Free running clock	
		<u>MOSI</u>	I/O	SPI master out / slave in	
		<u>(TXD1)</u>	I/O	Serial Communication Interface 1 transmit pin	
		<u>(PWM5)</u>	O	Pulse Width Modulator channel 5	
		<u>(ETRIG1)</u>	I	ADC external trigger input	
		PTS[3]	I/O	General-purpose	
	PS2	API_EXTCLK	O	CPMU API external clock output	
		<u>MISO</u>	I/O	SPI master in / slave out	
		<u>(RXD1)</u>	I	Serial Communication Interface 1 receive pin	
		<u>(PWM4)</u>	O	Pulse Width Modulator channel 4	
		<u>(ETRIG0)</u>	I	ADC external trigger input	
		PTS[2]	I/O	General-purpose	
	PS1	<u>TXD1</u>	I/O	Serial Communication Interface 1 transmit pin	
		<u>(LPDR1)</u>	O	LINPHY register LPDR[LPDR1]	
		<u>(TXD0)</u>	I/O	Serial Communication Interface 0 transmit pin	
		<u>PTS[1]</u>	I/O	General-purpose	
	PS0	<u>RXD1</u>	I	Serial Communication Interface 1 receive pin	
		<u>(RXD0)</u>	I	Serial Communication Interface 0 receive pin	
		<u>PTS[0]</u>	I/O	General-purpose	

Table 2-27. DDRP Register Field Descriptions (continued)

Field	Description
1 DDRP	Data Direction Register port P — This bit determines whether the associated pin is an input or output. The I/O state of the pin is forced to input level upon the first clearing of the X bit and held in this state even if the bit is set again. The PWM forces the I/O state to be an output for an enabled channel. In this case the data direction bit will not change. 1 Associated pin is configured as output 0 Associated pin is configured as input
0 DDRP	Data Direction Register port P — This bit determines whether the associated pin is an input or output. The PWM forces the I/O state to be an output for an enabled channel. In this case the data direction bit will not change. 1 Associated pin is configured as output 0 Associated pin is configured as input

2.3.29 Port P Reduced Drive Register (RDRP)

Address 0x025B (S12VR64/48)

Access: User read/write¹

	7	6	5	4	3	2	1	0
R	0	0	0	0	0	RDRP2	RDRP1	RDRP0
W								
Reset	0	0	0	0	0	0	0	0

Figure 2-39. Port P Reduced Drive Register (RDRP - S12VR64/48)

¹ Read: Anytime
Write: Anytime

Address 0x025B (S12VR32/16)

Access: User read/write¹

	7	6	5	4	3	2	1	0
R	0	0	0	0	0	RDRP2	RDRP1	0
W								
Reset	0	0	0	0	0	0	0	0

Figure 2-40. Port P Reduced Drive Register (RDRP - S12VR32/16)

¹ Read: Anytime
Write: Anytime

3.1.3 Features

The main features of this block are:

- Paging capability to support a global 256 KByte memory address space
- Bus arbitration between the masters CPU12, S12SBDM to different resources.
- MCU operation mode control
- MCU security control
- Generation of system reset when CPU12 accesses an unimplemented address (i.e., an address which does not belong to any of the on-chip modules) in single-chip modes

3.1.4 Modes of Operation

The S12GMMC selects the MCU's functional mode. It also determines the devices behavior in secured and unsecured state.

3.1.4.1 Functional Modes

Two functional modes are implemented on devices of the S12VR product family:

- Normal Single Chip (NS)
The mode used for running applications.
- Special Single Chip Mode (SS)
A debug mode which causes the device to enter BDM Active Mode after each reset. Peripherals may also provide special debug features in this mode.

3.1.4.2 Security

S12VR devices can be secured to prohibit external access to the on-chip flash. The S12GMMC module determines the access permissions to the on-chip memories in secured and unsecured state.

3.1.5 Block Diagram

Figure 3-1 shows a block diagram of the S12GMMC.

4.3.2.7 S12CPMU_UHV_V8 PLL Control Register (CPMUPLL)

This register controls the PLL functionality.

0x003A

	7	6	5	4	3	2	1	0
R	0	0	FM1	FM0	0	0	0	0
W								
Reset	0	0	0	0	0	0	0	0

Figure 4-10. S12CPMU_UHV_V8 PLL Control Register (CPMUPLL)

Read: Anytime

Write: Anytime if PROT=0 (CPMUPROT register) and PLLSEL=1 (CPMUCLKS register). Else write has no effect.

NOTE

Write to this register clears the LOCK and UPOSC status bits.

NOTE

Care should be taken to ensure that the bus frequency does not exceed the specified maximum when frequency modulation is enabled.

Table 4-8. CPMUPLL Field Descriptions

Field	Description
5, 4 FM1, FM0	PLL Frequency Modulation Enable Bits — FM1 and FM0 enable frequency modulation on the VCOCLK. This is to reduce noise emission. The modulation frequency is f_{ref} divided by 16. See Table 4-9 for coding.

Table 4-9. FM Amplitude selection

FM1	FM0	FM Amplitude / f_{VCO} Variation
0	0	FM off
0	1	$\pm 1\%$
1	0	$\pm 2\%$
1	1	$\pm 4\%$

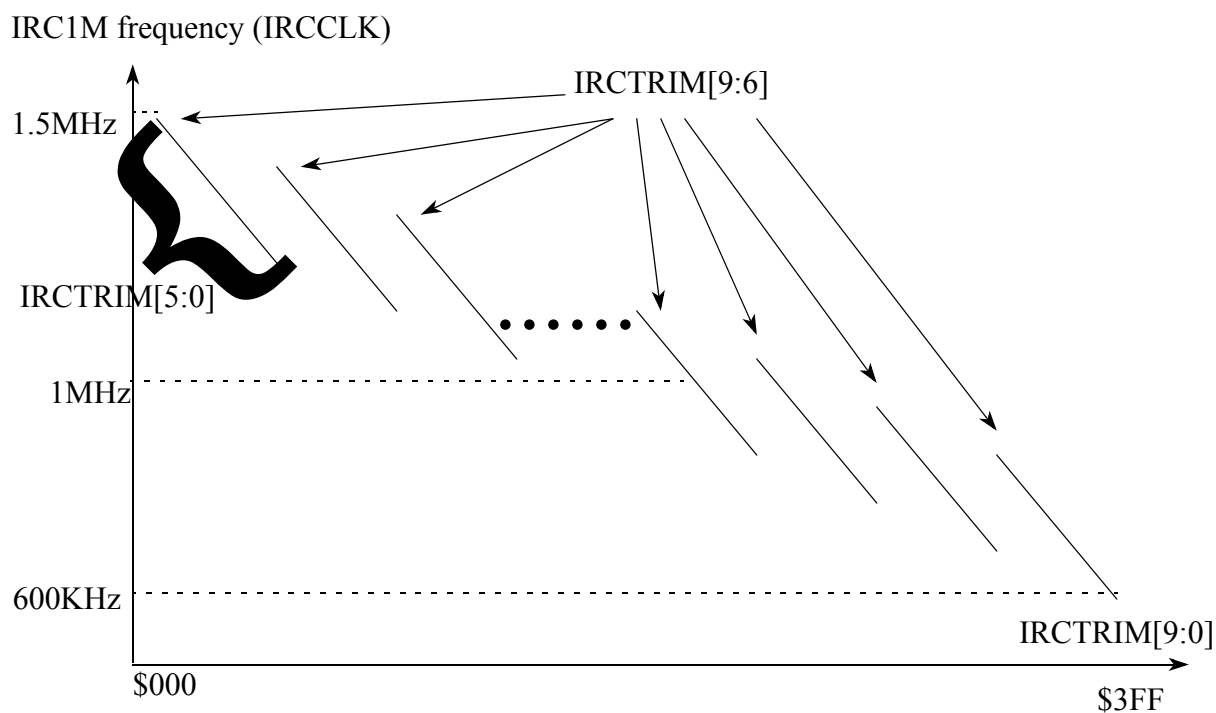


Figure 4-28. IRC1M Frequency Trimming Diagram

6.2 External Signal Description

There are no external signals associated with this module.

6.3 Memory Map and Registers

6.3.1 Module Memory Map

A summary of the registers associated with the DBG sub-block is shown in [Figure 6-2](#). Detailed descriptions of the registers and bits are given in the subsections that follow.

Address	Name		Bit 7	6	5	4	3	2	1	Bit 0
0x0020	DBGCI	R	ARM	0	0	BDM	DBGBRK	0	COMRV	
		W		TRIG						
0x0021	DBGSR	R	¹ TBF	0	0	0	0	SSF2	SSF1	SSF0
		W								
0x0022	DBGTCR	R	0	TSOURCE	0	0	TRCMOD	0		TALIGN
		W								
0x0023	DBGC2	R	0	0	0	0	0	0	ABCM	
		W								
0x0024	DBGTBH	R	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8
		W								
0x0025	DBGTBL	R	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
		W								
0x0026	DBGCNT	R	¹ TBF	0	CNT					
		W								
0x0027	DBGSCRX	R	0	0	0	0	SC3	SC2	SC1	SC0
		W								
0x0027	DBGMFR	R	0	0	0	0	0	MC2	MC1	MC0
		W								
² 0x0028	DBGACTL	R	SZE	SZ	TAG	BRK	RW	RWE	NDB	COMPE
		W								
³ 0x0028	DBGBCTL	R	SZE	SZ	TAG	BRK	RW	RWE	0	COMPE
		W								
⁴ 0x0028	DBGCCTL	R	0	0	TAG	BRK	RW	RWE	0	COMPE
		W								
0x0029	DBGXAH	R	0	0	0	0	0	0	Bit 17	Bit 16
		W								
0x002A	DBGXAM	R	Bit 15	14	13	12	11	10	9	Bit 8
		W								
0x002B	DBGXAL	R	Bit 7	6	5	4	3	2	1	Bit 0
		W								

Figure 6-2. Quick Reference to DBG Registers

of flow instruction, the trigger event is not stored in the Trace Buffer. If all trace buffer lines have been used before a trigger event occurs then the trace continues at the first line, overwriting the oldest entries.

6.4.5.2 Trace Modes

Four trace modes are available. The mode is selected using the TRCMOD bits in the DBGTCR register. Tracing is enabled using the TSOURCE bit in the DBGTCR register. The modes are described in the following subsections.

6.4.5.2.1 Normal Mode

In Normal Mode, change of flow (COF) program counter (PC) addresses are stored.

COF addresses are defined as follows:

- Source address of taken conditional branches (long, short, bit-conditional, and loop primitives)
- Destination address of indexed JMP, JSR, and CALL instruction
- Destination address of RTI, RTS, and RTC instructions
- Vector address of interrupts, except for BDM vectors

LBRA, BRA, BSR, BGND as well as non-indexed JMP, JSR, and CALL instructions are not classified as change of flow and are not stored in the trace buffer.

Stored information includes the full 18-bit address bus and information bits, which contains a source/destination bit to indicate whether the stored address was a source address or destination address.

NOTE

When a COF instruction with destination address is executed, the destination address is stored to the trace buffer on instruction completion, indicating the COF has taken place. If an interrupt occurs simultaneously then the next instruction carried out is actually from the interrupt service routine. The instruction at the destination address of the original program flow gets executed after the interrupt service routine.

In the following example an IRQ interrupt occurs during execution of the indexed JMP at address MARK1. The BRN at the destination (SUB_1) is not executed until after the IRQ service routine but the destination address is entered into the trace buffer to indicate that the indexed JMP COF has taken place.

	LDX	#SUB_1	
MARK1	JMP	0,X	; IRQ interrupt occurs during execution of this
MARK2	NOP		;
SUB_1	BRN	*	; JMP Destination address TRACE BUFFER ENTRY 1
			; RTI Destination address TRACE BUFFER ENTRY 3
	NOP		;
ADDR1	DBNE	A, PART5	; Source address TRACE BUFFER ENTRY 4
IRQ_ISR	LDAB	#\$F0	; IRQ Vector \$FFF2 = TRACE BUFFER ENTRY 2
	STAB	VAR_C1	

8.4 Functional Description

The ADC12B6CV2 consists of an analog sub-block and a digital sub-block.

8.4.1 Analog Sub-Block

The analog sub-block contains all analog electronics required to perform a single conversion. Separate power supplies VDDA and VSSA allow to isolate noise of other MCU circuitry from the analog sub-block.

8.4.1.1 Sample and Hold Machine

The Sample and Hold Machine controls the storage and charge of the sample capacitor to the voltage level of the analog signal at the selected ADC input channel.

During the sample process the analog input connects directly to the storage node.

The input analog signals are unipolar and must be within the potential range of VSSA to VDDA.

During the hold process the analog input is disconnected from the storage node.

8.4.1.2 Analog Input Multiplexer

The analog input multiplexer connects one of the 6 external analog input channels to the sample and hold machine.

8.4.1.3 Analog-to-Digital (A/D) Machine

The A/D Machine performs analog to digital conversions. The resolution is program selectable to be either 8 or 10 bits. The A/D machine uses a successive approximation architecture. It functions by comparing the sampled and stored analog voltage with a series of binary coded discrete voltages. By following a binary search algorithm, the A/D machine identifies the discrete voltage that is nearest to the sampled and stored voltage.

When not converting the A/D machine is automatically powered down.

Only analog input signals within the potential range of VRL to VRH (A/D reference potentials) will result in a non-railed digital output code.

8.4.2 Digital Sub-Block

This subsection describes some of the digital features in more detail. See [Section 8.3.2, “Register Descriptions”](#) for all details.

8.4.2.1 External Trigger Input

The external trigger feature allows the user to synchronize ATD conversions to an external event rather than relying only on software to trigger the ATD module when a conversions is about to take place. The external trigger signal (out of reset ATD channel 5, configurable in ATDCTL1) is programmable to be edge

10.3.2.3 SCI Alternative Status Register 1 (SCIASR1)

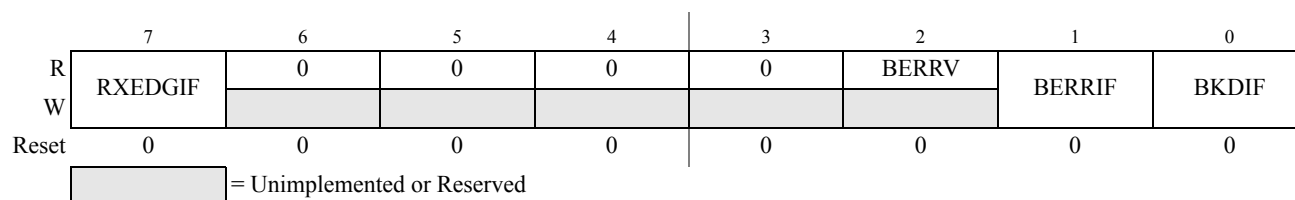


Figure 10-6. SCI Alternative Status Register 1 (SCIASR1)

Read: Anytime, if AMAP = 1

Write: Anytime, if AMAP = 1

Table 10-5. SCIASR1 Field Descriptions

Field	Description
7 RXEDGIF	Receive Input Active Edge Interrupt Flag — RXEDGIF is asserted, if an active edge (falling if RXPOL = 0, rising if RXPOL = 1) on the RXD input occurs. RXEDGIF bit is cleared by writing a “1” to it. 0 No active receive on the receive input has occurred 1 An active edge on the receive input has occurred
2 BERRV	Bit Error Value — BERRV reflects the state of the RXD input when the bit error detect circuitry is enabled and a mismatch to the expected value happened. The value is only meaningful, if BERRIF = 1. 0 A low input was sampled, when a high was expected 1 A high input reassembled, when a low was expected
1 BERRIF	Bit Error Interrupt Flag — BERRIF is asserted, when the bit error detect circuitry is enabled and if the value sampled at the RXD input does not match the transmitted value. If the BERRIE interrupt enable bit is set an interrupt will be generated. The BERRIF bit is cleared by writing a “1” to it. 0 No mismatch detected 1 A mismatch has occurred
0 BKDIF	Break Detect Interrupt Flag — BKDIF is asserted, if the break detect circuitry is enabled and a break signal is received. If the BKDIE interrupt enable bit is set an interrupt will be generated. The BKDIF bit is cleared by writing a “1” to it. 0 No break signal was received 1 A break signal was received

10.3.2.7 SCI Status Register 1 (SCISR1)

The SCISR1 and SCISR2 registers provides inputs to the MCU for generation of SCI interrupts. Also, these registers can be polled by the MCU to check the status of these bits. The flag-clearing procedures require that the status register be read followed by a read or write to the SCI data register. It is permissible to execute other instructions between the two steps as long as it does not compromise the handling of I/O, but the order of operations is important for flag clearing.

	7	6	5	4	3	2	1	0
R	TDRE	TC	RDRF	IDLE	OR	NF	FE	PF
W								
Reset	1	1	0	0	0	0	0	0

 = Unimplemented or Reserved

Figure 10-10. SCI Status Register 1 (SCISR1)

Read: Anytime

Write: Has no meaning or effect

Table 10-11. SCISR1 Field Descriptions

Field	Description
7 TDRE	Transmit Data Register Empty Flag — TDRE is set when the transmit shift register receives a byte from the SCI data register. When TDRE is 1, the transmit data register (SCIDRH/L) is empty and can receive a new value to transmit. Clear TDRE by reading SCI status register 1 (SCISR1), with TDRE set and then writing to SCI data register low (SCIDRL). 0 No byte transferred to transmit shift register 1 Byte transferred to transmit shift register; transmit data register empty
6 TC	Transmit Complete Flag — TC is set low when there is a transmission in progress or when a preamble or break character is loaded. TC is set high when the TDRE flag is set and no data, preamble, or break character is being transmitted. When TC is set, the TXD pin becomes idle (logic 1). Clear TC by reading SCI status register 1 (SCISR1) with TC set and then writing to SCI data register low (SCIDRL). TC is cleared automatically when data, preamble, or break is queued and ready to be sent. TC is cleared in the event of a simultaneous set and clear of the TC flag (transmission not complete). 0 Transmission in progress 1 No transmission in progress
5 RDRF	Receive Data Register Full Flag — RDRF is set when the data in the receive shift register transfers to the SCI data register. Clear RDRF by reading SCI status register 1 (SCISR1) with RDRF set and then reading SCI data register low (SCIDRL). 0 Data not available in SCI data register 1 Received data available in SCI data register
4 IDLE	Idle Line Flag — IDLE is set when 10 consecutive logic 1s (if M = 0) or 11 consecutive logic 1s (if M = 1) appear on the receiver input. Once the IDLE flag is cleared, a valid frame must again set the RDRF flag before an idle condition can set the IDLE flag. Clear IDLE by reading SCI status register 1 (SCISR1) with IDLE set and then reading SCI data register low (SCIDRL). 0 Receiver input is either active now or has never become active since the IDLE flag was last cleared 1 Receiver input has become idle Note: When the receiver wakeup bit (RWU) is set, an idle line condition does not set the IDLE flag.

10.5.3.1 Description of Interrupt Operation

The SCI only originates interrupt requests. The following is a description of how the SCI makes a request and how the MCU should acknowledge that request. The interrupt vector offset and interrupt number are chip dependent. The SCI only has a single interrupt line (SCI Interrupt Signal, active high operation) and all the following interrupts, when generated, are ORed together and issued through that port.

10.5.3.1.1 TDRE Description

The TDRE interrupt is set high by the SCI when the transmit shift register receives a byte from the SCI data register. A TDRE interrupt indicates that the transmit data register (SCIDRH/L) is empty and that a new byte can be written to the SCIDRH/L for transmission. Clear TDRE by reading SCI status register 1 with TDRE set and then writing to SCI data register low (SCIDRL).

10.5.3.1.2 TC Description

The TC interrupt is set by the SCI when a transmission has been completed. Transmission is completed when all bits including the stop bit (if transmitted) have been shifted out and no data is queued to be transmitted. No stop bit is transmitted when sending a break character and the TC flag is set (providing there is no more data queued for transmission) when the break character has been shifted out. A TC interrupt indicates that there is no transmission in progress. TC is set high when the TDRE flag is set and no data, preamble, or break character is being transmitted. When TC is set, the TXD pin becomes idle (logic 1). Clear TC by reading SCI status register 1 (SCISR1) with TC set and then writing to SCI data register low (SCIDRL). TC is cleared automatically when data, preamble, or break is queued and ready to be sent.

10.5.3.1.3 RDRF Description

The RDRF interrupt is set when the data in the receive shift register transfers to the SCI data register. A RDRF interrupt indicates that the received data has been transferred to the SCI data register and that the byte can now be read by the MCU. The RDRF interrupt is cleared by reading the SCI status register one (SCISR1) and then reading SCI data register low (SCIDRL).

10.5.3.1.4 OR Description

The OR interrupt is set when software fails to read the SCI data register before the receive shift register receives the next frame. The newly acquired data in the shift register will be lost in this case, but the data already in the SCI data registers is not affected. The OR interrupt is cleared by reading the SCI status register one (SCISR1) and then reading SCI data register low (SCIDRL).

10.5.3.1.5 IDLE Description

The IDLE interrupt is set when 10 consecutive logic 1s (if M = 0) or 11 consecutive logic 1s (if M = 1) appear on the receiver input. Once the IDLE is cleared, a valid frame must again set the RDRF flag before an idle condition can set the IDLE flag. Clear IDLE by reading SCI status register 1 (SCISR1) with IDLE set and then reading SCI data register low (SCIDRL).

16.4 Functional Description

16.4.1 General

The LIN Physical Layer module implements the physical layer of the LIN interface. This physical layer can be driven by the SCI (Serial Communication Interface) module or directly through the LPDR register.

16.4.2 Slew Rate and LIN Mode Selection

The slew rate can be selected for Electromagnetic Compatibility (EMC) optimized operation at 10.4 kbit/s and 20 kbit/s as well as at fast baud rate (up to 250 kbit/s) for test and programming. The slew rate can be chosen with the bits LPSLR[1:0] in the LIN Slew Rate Mode Register (LPSLRM). The default slew rate corresponds to 20 kbit/s.

The LIN Physical Layer can also be configured to be used for non-LIN applications (for example, to transmit a PWM pulse) by disabling the TxD-dominant timeout (LPDTDIS=1).

Changing the slew rate (LPSLRM Register) during transmission is not allowed in order to avoid unwanted effects. To change the register, the LIN Physical Layer must first be disabled (LPE=0). Once it is updated the LIN Physical Layer can be enabled again.

NOTE

For 20 kbit/s and Fast Mode communication speeds, the corresponding slew rate **MUST** be set; otherwise, the communication is not guaranteed (violation of the specified LIN duty cycles). For 10.4 kbit/s, the 20 kbit/s slew rate **can** be set but the EMC performance is worse. The up to 250 kbit/s slew rate must be chosen **ONLY** for fast mode, not for any of the 10.4 kbit/s or 20 kbit/s LIN compliant communication speeds.

16.4.2.1 10.4 kbit/s and 20 kbit/s

When the slew rate is chosen for 10.4 kbit/s or 20 kbit/s communication, a control loop is activated within the module to make the rise and fall times of the LIN bus independent from VLINSUP and the load on the bus.

16.4.2.2 Fast Mode (not LIN compliant)

Choosing this slew rate allows baud rates up to 250 kbit/s by having much steeper edges (please refer to electricals). As for the 10.4 kbit/s and 20 kbit/s modes, the slope control loop is also engaged. This mode is used for fast communication only, and the LIN electricals are not supported (for example, the LIN duty cycles).

A stronger external pullup resistor might be necessary to sustain communication speeds up to 250 kbit/s. The LIN signal (and therefore the receive LPRxD signal) might not be symmetrical for high baud rates with high loads on the bus.

18.5.2 Unsecuring the MCU in Special Single Chip Mode using BDM

A secured MCU can be unsecured in special single chip mode by using the following method to erase the P-Flash and EEPROM memory:

1. Reset the MCU into special single chip mode
2. Delay while the BDM executes the Erase Verify All Blocks command write sequence to check if the P-Flash and EEPROM memories are erased
3. Send BDM commands to disable protection in the P-Flash and EEPROM memory
4. Execute the Erase All Blocks command write sequence to erase the P-Flash and EEPROM memory. Alternatively the Unsecure Flash command can be executed, if so the steps 5 and 6 below are skipped.
5. After the CCIF flag sets to indicate that the Erase All Blocks operation has completed, reset the MCU into special single chip mode
6. Delay while the BDM executes the Erase Verify All Blocks command write sequence to verify that the P-Flash and EEPROM memory are erased

If the P-Flash and EEPROM memory are verified as erased, the MCU will be unsecured. All BDM commands will now be enabled and the Flash security byte may be programmed to the unsecure state by continuing with the following steps:

7. Send BDM commands to execute the Program P-Flash command write sequence to program the Flash security byte to the unsecured state
8. Reset the MCU

18.5.3 Mode and Security Effects on Flash Command Availability

The availability of Flash module commands depends on the MCU operating mode and security state as shown in [Table 18-27](#).

18.6 Initialization

On each system reset the flash module executes an initialization sequence which establishes initial values for the Flash Block Configuration Parameters, the FPROT and EEPROT protection registers, and the FOPT and FSEC registers. The initialization routine reverts to built-in default values that leave the module in a fully protected and secured state if errors are encountered during execution of the reset sequence. If a double bit fault is detected during the reset sequence, both MGSTAT bits in the FSTAT register will be set.

CCIF is cleared throughout the initialization sequence. The Flash module holds off all CPU access for a portion of the initialization sequence. Flash reads are allowed once the hold is removed. Completion of the initialization sequence is marked by setting CCIF high which enables user commands.

If a reset occurs while any Flash command is in progress, that command will be immediately aborted. The state of the word being programmed or the sector/block being erased is not guaranteed.

19.4.4.2 Command Write Sequence

The Memory Controller will launch all valid Flash commands entered using a command write sequence.

Before launching a command, the ACCERR and FPVIOL bits in the FSTAT register must be clear (see Section 19.3.2.7 Flash Status Register (FSTAT)) and the CCIF flag should be tested to determine the status of the current command write sequence. If CCIF is 0, the previous command write sequence is still active, a new command write sequence cannot be started, and all writes to the FCCOB register are ignored.

19.4.4.2.1 Define FCCOB Contents

The FCCOB parameter fields must be loaded with all required parameters for the Flash command being executed. Access to the FCCOB parameter fields is controlled via the CCOBIX bits in the FCCOBIX register (see Section 19.3.2.3 Flash CCOB Index Register (FCCOBIX)).

The contents of the FCCOB parameter fields are transferred to the Memory Controller when the user clears the CCIF command completion flag in the FSTAT register (writing 1 clears the CCIF to 0). The CCIF flag will remain clear until the Flash command has completed. Upon completion, the Memory Controller will return CCIF to 1 and the FCCOB register will be used to communicate any results. The flow for a generic command write sequence is shown in [Figure 19-26](#).

Table 19-49. Erase P-Flash Sector Command Error Handling

Register	Error Bit	Error Condition
FSTAT	ACCERR	Set if CCOBIX[2:0] != 001 at command launch
		Set if command not available in current mode (see Table 19-27)
		Set if an invalid global address [17:16] is supplied see Table 19-3)
		Set if a misaligned phrase address is supplied (global address [2:0] != 000)
	FPVIOL	Set if the selected P-Flash sector is protected
	MGSTAT1	Set if any errors have been encountered during the verify operation
	MGSTAT0	Set if any non-correctable errors have been encountered during the verify operation

19.4.6.10 Unsecure Flash Command

The Unsecure Flash command will erase the entire P-Flash and EEPROM memory space and, if the erase is successful, will release security.

Table 19-50. Unsecure Flash Command FCCOB Requirements

CCOBIX[2:0]	FCCOB Parameters	
000	0x0B	Not required

Upon clearing CCIF to launch the Unsecure Flash command, the Memory Controller will erase the entire P-Flash and EEPROM memory space and verify that it is erased. If the Memory Controller verifies that the entire Flash memory space was properly erased, security will be released. If the erase verify is not successful, the Unsecure Flash operation sets MGSTAT1 and terminates without changing the security state. During the execution of this command (CCIF=0) the user must not write to any Flash module register. The CCIF flag is set after the Unsecure Flash operation has completed.

Table 19-51. Unsecure Flash Command Error Handling

Register	Error Bit	Error Condition
FSTAT	ACCERR	Set if CCOBIX[2:0] != 000 at command launch
		Set if command not available in current mode (see Table 19-27)
	FPVIOL	Set if any area of the P-Flash or EEPROM memory is protected
	MGSTAT1	Set if any errors have been encountered during the verify operation
	MGSTAT0	Set if any non-correctable errors have been encountered during the verify operation

19.4.6.11 Verify Backdoor Access Key Command

The Verify Backdoor Access Key command will only execute if it is enabled by the KEYEN bits in the FSEC register (see [Table 19-10](#)). The Verify Backdoor Access Key command releases security if user-supplied keys match those stored in the Flash security bytes of the Flash configuration field (see [Table 19-4](#)). The Verify Backdoor Access Key command must not be executed from the Flash block containing the backdoor comparison key to avoid code runaway.

12b	Capacitance of the LIN pin, Recessive state	C_{LIN}			45	pF
13	Internal pull-up (slave)	R_{slave}	27	34	40	k Ω

¹For $3.5V \leq V_{LINSUP} < 5V$, the LINPHY is still working but with degraded parametrics.

²For $5V \leq V_{LINSUP} < 5.5V$, characterization showed that all parameters generally stay within the indicated specification, except the duty cycles D2 and D4 which may increase and potentially go beyond their maximum limits for highly loaded buses.

³The V_{LINSUP} voltage is provided by the VLINSUP supply. This supply mapping is described in device level documentation.

⁴At temperatures above 25C the current may be naturally limited by the driver, in this case the limitation circuit is not engaged and the flag is not set.

G.3 Dynamic Electrical Characteristics

Table G-3. Dynamic electrical characteristics of the LINPHY

Characteristics noted under conditions $5.5V \leq V_{LINSUP} \leq 18V$ unless otherwise noted ^{1 2 3} . Typical values noted reflect the approximate parameter mean at $T_A = 25^\circ C$ under nominal conditions unless otherwise noted.						
Num	Ratings	Symbol	Min	Typ	Max	Unit
1	Minimum duration of wake-up pulse generating a wake-up interrupt	t_{WUFR}	56	72	120	μs
2	TxD-dominant timeout (in IRC periods)	t_{DTLIM}	16388		16389	t_{IRC}
3	Propagation delay of receiver	t_{rx_pd}			6	μs
4	Symmetry of receiver propagation delay rising edge w.r.t. falling edge	t_{rx_sym}	-2		2	μs
LIN PHYSICAL LAYER: DRIVER CHARACTERISTICS FOR NOMINAL SLEW RATE - 20.0KBIT/S						
5	Rising/falling edge time (min to max / max to min)	t_{rise}		6.5		μs
6	Over-current masking window (IRC trimmed at 1MHz)	t_{OCLIM}	15		16	μs
7	Duty cycle 1 $T_{HRec(max)} = 0.744 \times V_{LINSUP}$ $T_{HDom(max)} = 0.581 \times V_{LINSUP}$ $V_{LINSUP} = 5.5V \dots 18V$ $t_{Bit} = 50\mu s$ $D1 = t_{Bus_rec(min)} / (2 \times t_{Bit})$	D1	0.396			
8	Duty cycle 2 $T_{HRec(min)} = 0.422 \times V_{LINSUP}$ $T_{HDom(min)} = 0.284 \times V_{LINSUP}$ $V_{LINSUP} = 5.5V \dots 18V$ $t_{Bit} = 50\mu s$ $D2 = t_{Bus_rec(max)} / (2 \times t_{Bit})$	D2			0.581	
LIN PHYSICAL LAYER: DRIVER CHARACTERISTICS FOR SLOW SLEW RATE - 10.4KBIT/S						
9	Rising/falling edge time (min to max / max to min)	t_{rise}		13		μs
10	Over-current masking window (IRC trimmed at 1MHz)	t_{OCLIM}	31		32	μs

P.9 0x0020-0x002F Debug Module (S12SDBG) Map

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
0x002B	DBGXAL	R W	Bit 7	6	5	4	3	2	1	Bit 0
0x002C	DBGADH	R W	Bit 15	14	13	12	11	10	9	Bit 8
0x002D	DBGADL	R W	Bit 7	6	5	4	3	2	1	Bit 0
0x002E	DBGADHM	R W	Bit 15	14	13	12	11	10	9	Bit 8
0x002F	DBGADLM	R W	Bit 7	6	5	4	3	2	1	Bit 0

¹ This represents the contents if the Comparator A or C control register is blended into this address

² This represents the contents if the Comparator B or D control register is blended into this address

³ This represents the contents if the Comparator B or D control register is blended into this address

P.10 0x0030-0x0033 Reserved

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
0x0030	Reserved	R W	0	0	0	0	0	0	0	0
0x0031	Reserved	R W	0	0	0	0	0	0	0	0
0x0032	Reserved	R W	0	0	0	0	0	0	0	0
0x0033	Reserved	R W	0	0	0	0	0	0	0	0

P.11 0x0034-0x003F Clock Reset and Power Management (CPMU) Map

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
0x0034	CPMUSYNR	R W	VCOFRQ[1:0]		SYNDIV[5:0]					
0x0035	CPMUREFDIV	R W	REFFRQ[1:0]		0	0	REFDIV[3:0]			
0x0036	CPMUPOSTDIV	R W	0	0	0	POSTDIV[4:0]				
0x0037	CPMUFLG	R W	RTIF	PORF	LVRF	LOCKIF	LOCK	ILAF	OSCIF	UPOSC
0x0038	CPMUINT	R W	RTIE	0	0	LOCKIE	0	0	OSCIE	PMRF ¹
0x0039	CPMUCLKS	R W	PLLSEL	PSTP	0	COPOSCSEL1	PRE	PCE	RTIOSCSCEL	COPOSCSEL0